IPC ASSOCIATION ELECTRONIC	Material Composition © Copyright 2005. Il	PC, Bannockb	urn, Illinois. A	all rights reserved un	ider both	This docume level parts, the	ent is a declara he declaration	ation of encom	the substances npasses all lowe	within th	e manufactur aterials for w	rer listed it hich the m	em. Note: anufacture	if the item is an as er has engineering	sembly with low responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information					
Supplier	Information															
Company name* Compa				ompany unique ID			Unique ID Authority					Response Date*				
nsemi													2024-05-04			
Contact N	ame		Title - Contact				Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorize	d Representative*		Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufactur		uring Site	Site Weight*		UOM	Unit Type			
		LC75832EH-E L		LCD Display Driver			2024-05-04]	PHM		1	100.0	mg	Each	
I anufa	cturing Proccess Informat	tion														
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020 N		STD-020 MSL	Rating	Peak Process Body Temperar		ody Temperatu	ture Max Time at Peak Temper		Temperatu	ire Num	nber of Reflow Cyc	eles	
contains Bi		CU Alloy 4			260 C		30 seco		second	ls 3						
omments																
or more	information regarding material	composition j	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others, on the part and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.98	mg	Supplier	Silicon (Si)	7440-21-3		4.9491	mg
			Supplier	Polyimide	Proprietary Data		0.0309	mg
Die Attach	0.41	mg	Supplier	Silver (Ag)	7440-22-4		0.3136	mg
			Supplier	Epoxy resins	129915-35-1		0.0963	mg
Lead Frame	250.62	mg	Supplier	Silver (Ag)	7440-22-4		0.6015	mg
			Supplier	Tin (Sn)	7440-31-5		0.6516	mg
			Supplier	Zinc (Zn)	7440-66-6		0.6265	mg
			Supplier	Chromium (Cr)	7440-47-3		0.6767	mg
			Supplier	Copper (Cu)	7440-50-8		248.0637	mg
Mold Compound-Black	835.66	mg		Brominated epoxy resin	proprietary data		8.3566	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		116.9924	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		16.7132	mg
			Supplier	Carbon Black (C)	1333-86-4		3.3426	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		673.5419	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		16.7132	mg
Plating	6.81	mg	В	Bismuth (Bi)	7440-69-9		0.0409	mg
			Supplier	Tin (Sn)	7440-31-5		6.7691	mg
Wire Bond - Au	1.52	mg	Supplier	Gold (Au)	7440-57-5		1.52	mg